

APPENDIX

Changes to Claims:

Claims 3, 9 and 17-20 are canceled.

Claims 21 and 22 are added.

The following are marked-up versions of amended claims 1, 2, 8, 14 and 15:

1. (Twice Amended) A method of manufacturing a semiconductor device comprising:

a first step of interposing a ~~first adhesive portion of~~ an adhesive between a surface of a substrate on which an interconnect pattern is formed and a surface of a semiconductor chip on which electrodes are formed, and ~~interposing a second adhesive portion of the adhesive formed next to said first adhesive portion and on at least a part of a lateral surface of said semiconductor chip;~~ and

a second step in which pressure is applied between said semiconductor chip and said substrate, said interconnect pattern and said electrodes are electrically connected, and said adhesive is caused to cover substantially all ~~surround at least a part of~~ ~~at the~~ lateral surface of said semiconductor chip, ~~at least a part of said second adhesive portion having a thickness greater than the first adhesive portion.~~

2. (Amended) The method of manufacturing a semiconductor device as defined in claim 1,

wherein said adhesive is provided in the first step at a thickness greater than the interval between said semiconductor chip and said substrate after the second step, and is ~~spread out beyond said semiconductor chip by applying pressure between said semiconductor chip and said substrate in the second step.~~

8. (Twice Amended) A semiconductor device, comprising:
a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive;

wherein said electrodes and said interconnect pattern are electrically connected; and

wherein said adhesive is has a first portion interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said adhesive covers substantially all of a second portion formed next to said first portion and on at least a part of lateral surface of said semiconductor chip at least a part of said second portion having a thickness greater than said first portion.

14. (Amended) A circuit board on which is mounted at the semiconductor device as defined in claim 8, the semiconductor device comprising:

a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive;

wherein said electrodes and said interconnect pattern are electrically connected; and

wherein said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said adhesive covers substantially all of a lateral surface of said semiconductor chip.

15. (Amended) An electronic instrument having the circuit board as defined in claim 14 a semiconductor device, the semiconductor device comprising:

a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive;

wherein said electrodes and said interconnect pattern are electrically connected; and

wherein said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said adhesive covers substantially all of a lateral surface of said semiconductor chip.